Module 2

Lesson 2

Activities inside the cleanroom area

First, we have the incoming wafer carrier which holds the wafers.

When the wafers arrive they only have the chips on the front side and the back is just the supporting substrate and that substrate makes the wafer very thick. So before processing we need to make the wafer as thin as possible.

1. Wafer inspection – to check whether the wafer is of good quality, not damaged and processible.
2. After that is checked we have wafer front tape lamination to protect the processing on the front of the wafer.
3. Then we have the wafer backside grinding. For this process the wafer and flipped and put on a chuck table which is rotated at high speeds while a mechanical force is applied. This force erodes the excess silicon.